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April 1999



**ON Semiconductor®** 

# FDS6961A

# Dual N-Channel Logic Level PowerTrench<sup>™</sup> MOSFET

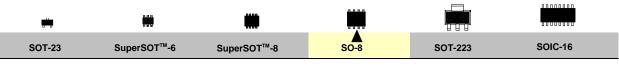
### **General Description**

These N-Channel Logic Level MOSFETs are produced using ON Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

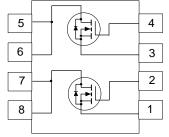
These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

## Features

- $\begin{array}{c|c} \bullet & 3.5 \text{ A}, \ 30 \text{ V}. \ R_{_{DS(ON)}} = 0.090 \ \Omega & @ \ V_{_{GS}} = 10 \ V \\ & R_{_{DS(ON)}} = 0.140 \ \Omega & @ \ V_{_{GS}} = 4.5 \ V. \end{array}$
- Fast switching speed.
- Low gate charge (2.1nC typical).
- High performance trench technology for extremely low R<sub>DS(ON)</sub>.
- High power and current handling capability.





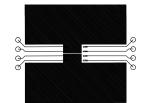


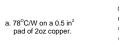
### **Absolute Maximum Ratings** $T_A = 25^{\circ}C$ unless other wise noted

| Symbol               | Parameter   | Ratings    | Units |
|----------------------|---|------------|-------|
| V <sub>DSS</sub>     | Drain-Source Voltage                              | 30         | V     |
| $V_{GSS}$            | Gate-Source Voltage                               | ±20        | V     |
| I <sub>D</sub>       | Drain Current - Continuous (Note 1a)              | 3.5        | A     |
|                      | - Pulsed  | 14         |       |
| P <sub>D</sub>       | Power Dissipation for Single Operation (Note 1)   | 2          | W     |
|                      | Power Dissipation for Single Operation (Note 1a)  | 1.6        |       |
|                      | (Note 1b)   | 1          |       |
|                      | (Note 1c)   | 0.9        |       |
| T_,,T <sub>stg</sub> | Operating and Storage Temperature Range           | -55 to 150 | C°    |
| THERMA               | L CHARACTERISTICS                                 |            | ·     |
| R <sub>eja</sub>     | Thermal Resistance, Junction-to-Ambient (Note 1a) | 78         | °C/W  |
| R <sub>ejic</sub>    | Thermal Resistance, Junction-to-Case (Note 1)     | 40         | °C/W  |

| Symbol                           | Parameter                                 | Conditions  | Min | Тур   | Max   | Units |
|----------------------------------|---|---|-----|-------|-------|-------|
| OFF CHAR                         | ACTERISTICS                               |   |     |       |       |       |
| BV <sub>DSS</sub>                | Drain-Source Breakdown Voltage            | $V_{GS} = 0 V, I_{D} = 250 \mu A$   | 30  |       |       | V     |
| $\Delta BV_{DSS} / \Delta T_{J}$ | Breakdown Voltage Temp. Coefficient       | $I_D = 250 \ \mu\text{A}$ , Referenced to $25 \ ^{\circ}\text{C}$             |     | 25    |       | mV/ºC |
| I <sub>DSS</sub>                 | Zero Gate Voltage Drain Current           | $V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$<br>$T_{J} = 55^{\circ}\text{C}$ |     |       | 1     | μA    |
|                                  |   |   |     |       | 10    | μA    |
|                                  | Gate - Body Leakage, Forward              | $V_{GS} = 20 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$                         |     |       | 100   | nA    |
|                                  | Gate - Body Leakage, Reverse              | $V_{GS} = -20 V, V_{DS} = 0 V$  |     |       | -100  | nA    |
| ON CHARA                         | CTERISTICS (Note 2)                       |   |     |       |       |       |
| V <sub>GS(th)</sub>              | Gate Threshold Voltage                    | $V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$  | 1   | 1.8   | 3     | V     |
| $\Delta V_{GS(th)} / \Delta T_J$ | Gate Threshold Voltage Temp. Coefficient  | $I_{D}$ = 250 µA, Referenced to 25 °C   |     | -5    |       | mV/ºC |
| R <sub>DS(ON)</sub>              | Static Drain-Source On-Resistance         | $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3.5 \text{ A}$                        |     | 0.076 | 0.09  | Ω     |
| . ,                              |   | T <sub>.1</sub> =125°C  |     | 0.11  | 0.155 |       |
|                                  |   | $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 2.8 \text{ A}$                       |     | 0.107 | 0.14  |       |
| I <sub>D(ON)</sub>               | On-State Drain Current                    | $V_{gs} = 10 V, V_{Ds} = 5 V$   | 14  |       |       | Α     |
| 9 <sub>FS</sub>                  | Forward Transconductance                  | $V_{DS} = 15 \text{ V}, \text{ I}_{D} = 3.5 \text{ A}$                        |     | 6     |       | S     |
| DYNAMIC C                        | HARACTERISTICS                            |   |     |       |       |       |
| C <sub>iss</sub>                 | Input Capacitance                         | $V_{DS} = 15 V, V_{GS} = 0 V,$<br>f = 1.0 MHz                                 |     | 220   |       | pF    |
| C <sub>oss</sub>                 | Output Capacitance                        | f = 1.0  MHz  |     | 50    |       | pF    |
| C <sub>rss</sub>                 | Reverse Transfer Capacitance              |   |     | 20    |       | pF    |
| SWITCHING                        | CHARACTERISTICS (Note 2)                  |   |     |       |       |       |
| t <sub>D(on)</sub>               | Tum - On Delay Time                       | $V_{DS} = 15 \text{ V}, \text{ I}_{D} = 1 \text{ A}$                          |     | 3     | 6     | ns    |
| t,                               | Turn - On Rise Time                       | $V_{_{GS}} = 10 \text{ V} \text{ , } \text{ R}_{_{GEN}} = 6 \Omega$           |     | 11    | 22    | ns    |
| t <sub>D(off)</sub>              | Turn - Off Delay Time                     |   |     | 7     | 14    | ns    |
| t,                               | Turn - Off Fall Time                      |   |     | 3     | 6     | ns    |
| Qg                               | Total Gate Charge                         | $V_{\rm DS} = 15 \text{ V}, \ \text{I}_{\rm D} = 3.5 \text{ A},$              |     | 2.1   | 4     | nC    |
| Q <sub>gs</sub>                  | Gate-Source Charge                        | $V_{GS} = 5 V$  |     | 0.8   |       | nC    |
| Q <sub>gd</sub>                  | Gate-Drain Charge                         |   |     | 0.7   |       | nC    |
| DRAIN-SOU                        | RCE DIODE CHARACTERISTICS AND MAXIMU      | JM RATINGS  |     |       |       |       |
| l <sub>s</sub>                   | Maximum Continuous Drain-Source Diode For | Forward Current   |     |       | 1.3   | А     |
| V <sub>SD</sub>                  | Drain-Source Diode Forward Voltage        | $V_{GS} = 0 V, I_{S} = 1.3 A$ (Note 2)  |     | 0.73  | 1.2   | V     |

1. R<sub>gut</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>gut</sub> is guaranteed by design while R<sub>gut</sub> is determined by the user's board design.

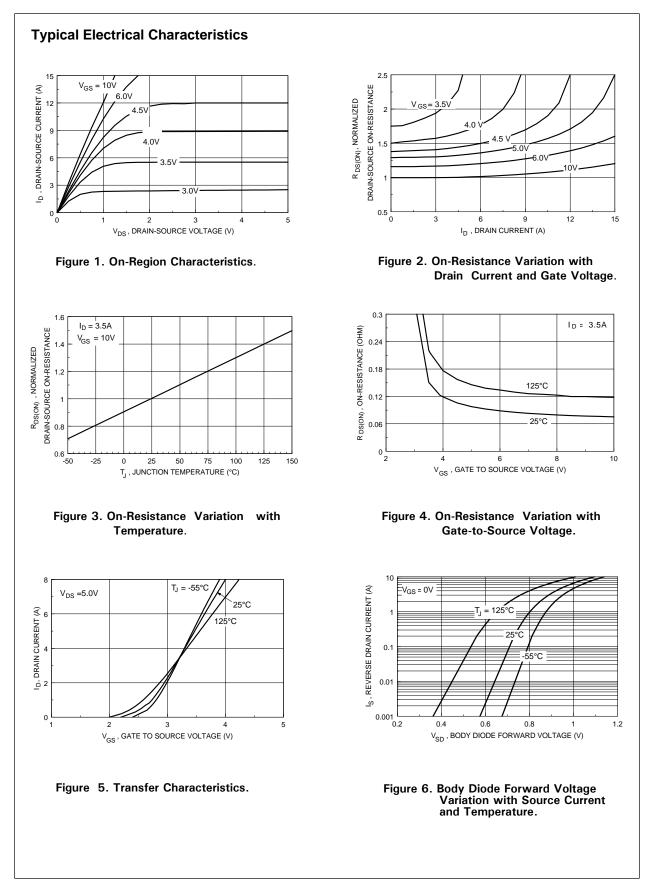




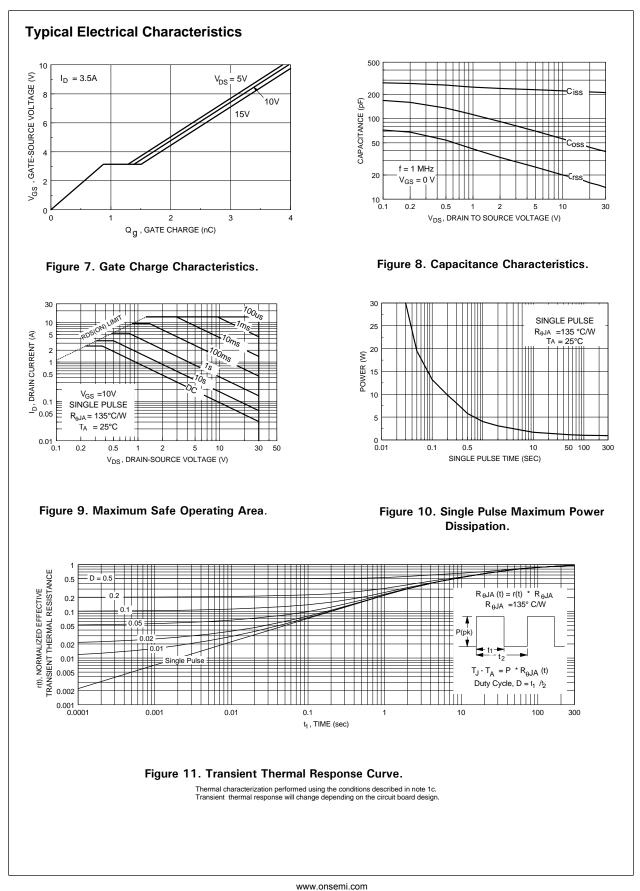
b. 125°C/W on a 0.02 in<sup>2</sup> pad of 20z copper.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2.0%.



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